

## Features

- Operating voltage: 2.7V~5.2V
- Built-in RC oscillator
- External 32.768kHz crystal or 32kHz frequency source input
- 1/5 bias, 1/16 duty, frame frequency is 64Hz
- Max. 48×16 patterns, 16 commons, 48 segments
- Built-in internal resistor type bias generator
- 3-wire serial interface
- 8 kinds of time base/WDT selection
- Time base or WDT overflow output
- Built-in LCD display RAM
- R/W address auto increment
- Two selection buzzer frequencies (2kHz/4kHz)
- Power down command reduces power consumption
- Software configuration feature
- Data mode and Command mode instructions
- Three data accessing modes
- VLCD pin to adjust LCD operating voltage
- Cascade application

## General Description

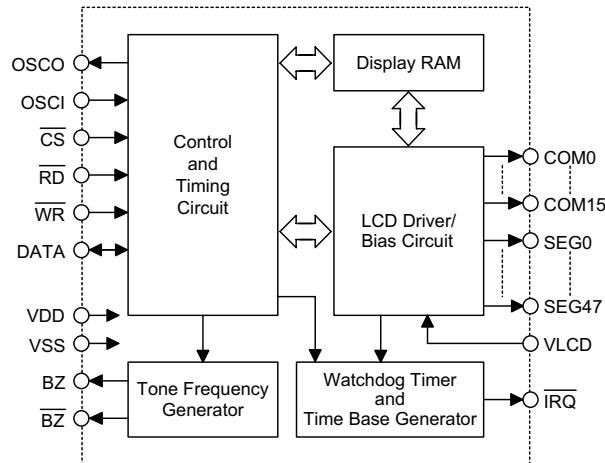
HT1626 is a peripheral device specially designed for I/O type μC used to expand the display capability. The max. display segment of the device are 768 patterns (48×16). It also supports serial interface, buzzer sound, Watchdog Timer or time base timer functions. The HT1626 is a memory mapping and multi-function LCD controller. The software

configuration feature of the HT1626 make it suitable for multiple LCD applications including LCD modules and display subsystems. Only three lines are required for the interface between the host controller and the HT1626. The HT162X series have many kinds of products that match various applications.

## Selection Table

HT162X	HT1620	HT1621	HT1622	HT16220	HT1623	HT1625	HT1626
<b>COM</b>	4	4	8	8	8	8	<b>16</b>
<b>SEG</b>	32	32	32	32	48	64	<b>48</b>
<b>Built-in Osc.</b>		√	√		√	√	√
<b>Crystal Osc.</b>	√	√		√	√	√	√

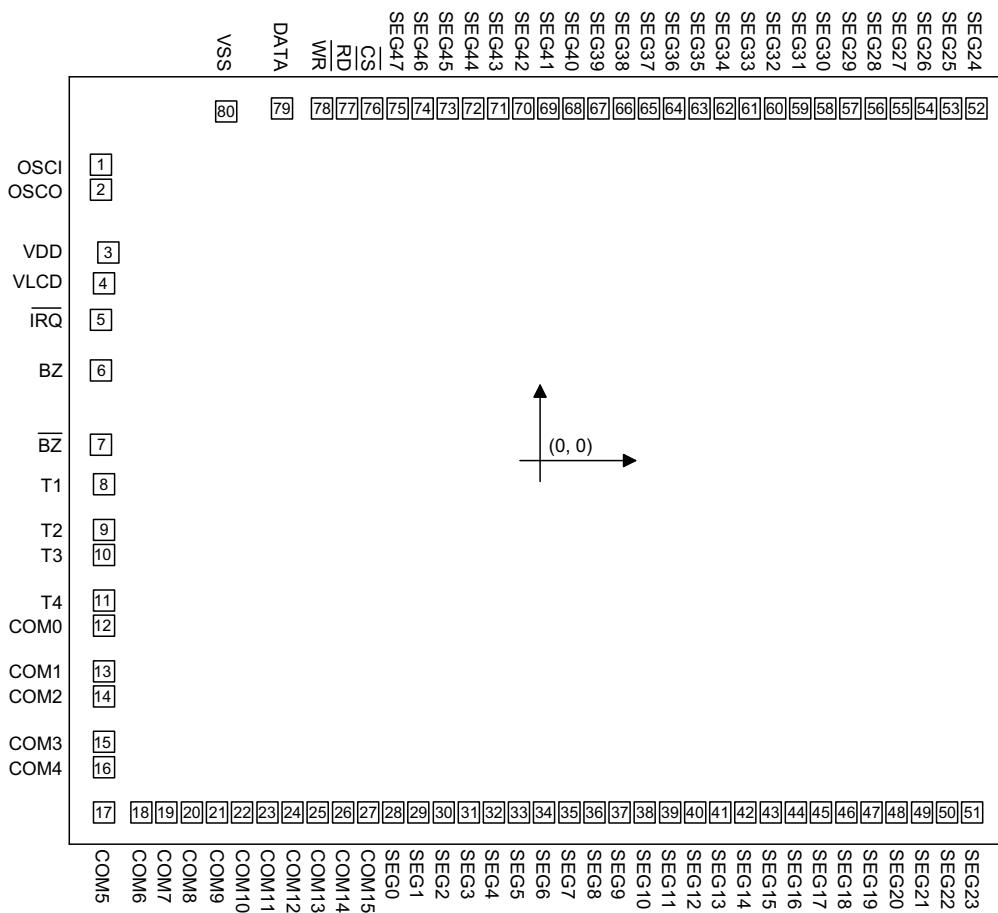
## Block Diagram



## Pin Assignment

	100 99 98 97 96 95 94 93 92 91 90 89 88 87 86 85 84 83 82 81	SEG30 SEG31 SEG32 SEG33 SEG34 SEG35 SEG36 SEG37 SEG38 SEG39 SEG40 SEG41 SEG42 SEG43 SEG44 SEG45 SEG46 SEG47
WR	1	80 SEG29
DATA	2	79 SEG28
NC	3	78 SEG27
NC	4	77 SEG26
VSS	5	76 SEG25
OSCI	6	75 SEG24
OSCO	7	74 NC
VDD	8	73 NC
VLCD	9	72 NC
IRQ	10	71 NC
BZ	11	70 NC
$\bar{BZ}$	12	69 NC
T1	13	68 NC
T2	14	67 NC
T3	15	66 NC
T4	16	65 NC
COM0	17	64 NC
COM1	18	63 NC
COM2	19	62 NC
COM3	20	61 NC
COM4	21	60 NC
NC	22	59 NC
COM5	23	58 NC
COM6	24	57 SEG23
COM7	25	56 SEG22
COM8	26	55 SEG21
COM9	27	54 SEG20
COM10	28	53 SEG19
COM11	29	52 SEG18
COM12	30	51 SEG17
	31 32 33 34 35 36 37 38 39 40 41 42 43 44 45 46 47 48 49 50	SEG15 SEG16 SEG17 SEG18 SEG19 SEG20 SEG21 SEG22 SEG23 SEG24 SEG25 SEG26 SEG27 SEG28 SEG29 SEG30 SEG31 SEG32 SEG33 SEG34 SEG35 SEG36 SEG37 SEG38 SEG39 SEG40 SEG41 SEG42 SEG43 SEG44 SEG45 SEG46 SEG47
COM13		
COM14		
COM15		
SEG0		
SEG1		
SEG2		
SEG3		
SEG4		
SEG5		
SEG6		
SEG7		
SEG8		
SEG9		
SEG10		
SEG11		
SEG12		
SEG13		
SEG14		
SEG15		
SEG16		

## Pad Assignment



Chip size:  $242 \times 196$  (mil)<sup>2</sup>

\* The IC substrate should be connected to VDD in the PCB layout artwork.

**Pad Coordinates**

Unit: mil

<b>Pad No.</b>	<b>X</b>	<b>Y</b>	<b>Pad No.</b>	<b>X</b>	<b>Y</b>
1	-115.68	77.99	41	47.47	-92.74
2	-115.68	71.36	42	54.10	-92.74
3	-113.69	54.83	43	60.73	-92.74
4	-114.92	46.62	44	67.36	-92.74
5	-115.68	37.10	45	73.99	-92.74
6	-115.68	23.80	46	80.62	-92.74
7	-115.68	4.21	47	87.25	-92.74
8	-114.92	-6.29	48	93.88	-92.74
9	-114.92	-18.27	49	100.51	-92.74
10	-114.92	-24.91	50	107.14	-92.74
11	-114.92	-36.89	51	113.77	-92.74
12	-114.92	-43.52	52	114.88	92.74
13	-114.92	-55.51	53	108.25	92.74
14	-114.92	-62.13	54	101.62	92.74
15	-114.92	-74.12	55	94.99	92.74
16	-114.92	-80.75	56	88.36	92.74
17	-114.92	-92.74	57	81.73	92.74
18	-105.02	-92.74	58	75.10	92.74
19	-98.39	-92.74	59	68.47	92.74
20	-91.76	-92.74	60	61.84	92.74
21	-85.13	-92.74	61	55.21	92.74
22	-78.50	-92.74	62	48.58	92.74
23	-71.87	-92.74	63	41.95	92.74
24	-65.24	-92.74	64	35.32	92.74
25	-58.61	-92.74	65	28.69	92.74
26	-51.98	-92.74	66	22.06	92.74
27	-45.35	-92.74	67	15.43	92.74
28	-38.72	-92.74	68	8.80	92.74
29	-32.09	-92.74	69	2.17	92.74
30	-25.46	-92.74	70	-4.46	92.74
31	-18.83	-92.74	71	-11.09	92.74
32	-12.20	-92.74	72	-17.72	92.74
33	-5.57	-92.74	73	-24.35	92.74
34	1.06	-92.74	74	-30.98	92.74
35	7.69	-92.74	75	-37.61	92.74
36	14.32	-92.74	76	-44.24	92.74
37	20.95	-92.74	77	-50.87	92.74
38	27.58	-92.74	78	-57.50	92.74
39	34.21	-92.74	79	-68.04	92.74
40	40.84	-92.74	80	-82.71	91.97

### **Pad Description**

<b>Pad No.</b>	<b>Pad Name</b>	<b>I/O</b>	<b>Description</b>
1	OSCI	I	The OSCI and OSCO pads are connected to a 32.768kHz crystal in order to generate a system clock. If the system clock comes from an external clock source, the external clock source should be connected to the OSCI pad. But if an on-chip RC oscillator is selected instead, the OSCI and OSCO pads can be left open.
2	OSCO	O	
3	VDD	—	Positive power supply
4	VLCD	I	LCD operating voltage input pad.
5	$\overline{IRQ}$	O	Time base or Watchdog Timer overflow flag, NMOS open drain output
6, 7	BZ, $\overline{BZ}$	O	2kHz or 4kHz tone frequency output pair
8~11	T1~T4	I	Not connected
12~27	COM0~COM15	O	LCD common outputs
28~75	SEG0~SEG47	O	LCD segment outputs
76	$\overline{CS}$	I	Chip selection input with pull-high resistor. When the $\overline{CS}$ is logic high, the data and command read from or write to the HT1626 are disabled. The serial interface circuit is also reset. But if the $\overline{CS}$ is at logic low level and is input to the $\overline{CS}$ pad, the data and command transmission between the host controller and the HT1626 are all enabled.
77	$\overline{RD}$	I	READ clock input with pull-high resistor. Data in the RAM of the HT1626 are clocked out on the rising edge of the $\overline{RD}$ signal. The clocked out data will appear on the data line. The host controller can use the next falling edge to latch the clocked out data.
78	$\overline{WR}$	I	WRITE clock input with pull-high resistor. Data on the DATA line are latched into the HT1626 on the rising edge of the $\overline{WR}$ signal.
79	DATA	I/O	Serial data input/output with pull-high resistor
80	VSS	—	Negative power supply, ground

### **Absolute Maximum Ratings**

Supply Voltage.....	-0.3V to 5.5V	Storage Temperature.....	-50°C to 125°C
Input Voltage .....	$V_{SS}$ -0.3V to $V_{DD}$ +0.3V	Operating Temperature .....	-25°C to 75°C

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

**D.C. Characteristics**

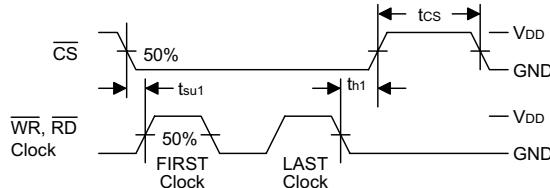
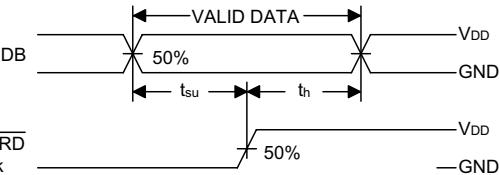
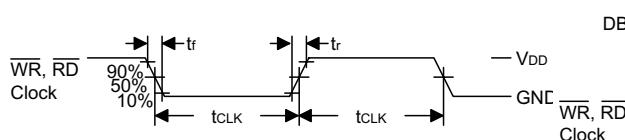
Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V <sub>DD</sub>	Conditions				
V <sub>DD</sub>	Operating Voltage	—	—	2.7	—	5.2	V
I <sub>DD1</sub>	Operating Current	3V	No load/LCD ON	—	155	310	μA
		5V	On-chip RC oscillator	—	260	420	μA
I <sub>DD2</sub>	Operating Current	3V	No load/LCD ON	—	150	310	μA
		5V	Crystal oscillator	—	250	420	μA
I <sub>DD11</sub>	Operating Current	3V	No load/LCD OFF	—	8	30	μA
		5V	On-chip RC oscillator	—	20	60	μA
I <sub>DD22</sub>	Operating Current	3V	No load/LCD OFF	—	—	20	μA
		5V	Crystal oscillator	—	—	35	μA
I <sub>STB</sub>	Standby Current	3V	No load	—	1	12	μA
		5V	Power down mode	—	2	24	μA
V <sub>IL</sub>	Input Low Voltage	3V	DATA, WR, CS, RD	0	—	0.6	V
		5V		0	—	1.0	V
V <sub>IH</sub>	Input High Voltage	3V	DATA, WR, CS, RD	2.4	—	3	V
		5V		4.0	—	5	V
I <sub>OL1</sub>	BZ, $\overline{BZ}$ , $\overline{IRQ}$	3V	V <sub>OL</sub> =0.3V	0.9	1.8	—	mA
		5V	V <sub>OL</sub> =0.5V	1.7	3	—	mA
I <sub>OH1</sub>	BZ, $\overline{BZ}$	3V	V <sub>OH</sub> =2.7V	-0.9	-1.8	—	mA
		5V	V <sub>OH</sub> =4.5V	-1.7	-3	—	mA
I <sub>OL1</sub>	DATA	3V	V <sub>OL</sub> =0.3V	0.9	1.8	—	mA
		5V	V <sub>OL</sub> =0.5V	1.7	3	—	mA
I <sub>OH1</sub>	DATA	3V	V <sub>OH</sub> =2.7V	-0.9	-1.8	—	mA
		5V	V <sub>OH</sub> =4.5V	-1.7	-3	—	mA
I <sub>OL2</sub>	LCD Common Sink Current	3V	V <sub>OL</sub> =0.3V	80	160	—	μA
		5V	V <sub>OL</sub> =0.5V	180	360	—	μA
I <sub>OH2</sub>	LCD Common Source Current	3V	V <sub>OH</sub> =2.7V	-40	-80	—	μA
		5V	V <sub>OH</sub> =4.5V	-90	-180	—	μA
I <sub>OL3</sub>	LCD Segment Sink Current	3V	V <sub>OL</sub> =0.3V	50	100	—	μA
		5V	V <sub>OL</sub> =0.5V	120	240	—	μA
I <sub>OH3</sub>	LCD Segment Source Current	3V	V <sub>OH</sub> =2.7V	-30	-60	—	μA
		5V	V <sub>OH</sub> =4.5V	-70	-140	—	μA
R <sub>PH</sub>	Pull-high Resistor	3V	DATA, WR, CS, RD	100	200	300	kΩ
		5V		50	100	150	kΩ

**A.C. Characteristics**

Ta=25°C

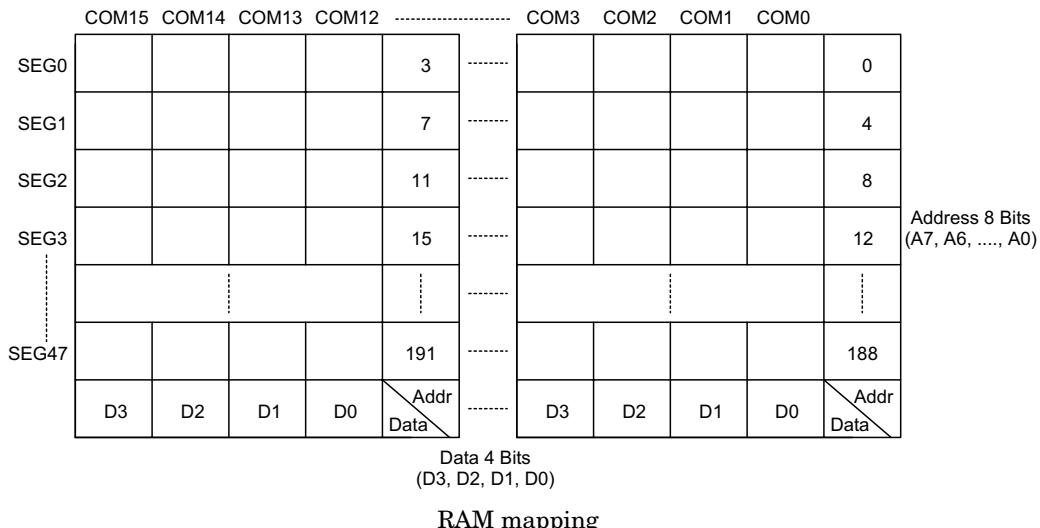
<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>		<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
		<b>V<sub>DD</sub></b>	<b>Conditions</b>				
f <sub>SYS1</sub>	System Clock	3V	On-chip RC oscillator	22	32	40	kHz
		5V		24	32	40	kHz
f <sub>SYS2</sub>	System Clock	3V	External clock source	—	32	—	kHz
		5V		—	32	—	kHz
f <sub>LCD1</sub>	LCD Frame Frequency	3V	On-chip RC oscillator	44	64	80	Hz
		5V		48	64	80	Hz
f <sub>LCD2</sub>	LCD Frame Frequency	3V	External clock source	—	64	—	Hz
		5V		—	64	—	Hz
t <sub>COM</sub>	LCD Common Period	—	n: Number of COM	—	n/f <sub>LCD</sub>	—	sec
f <sub>CLK1</sub>	Serial Data Clock ( $\overline{WR}$ Pin)	3V	Duty cycle 50%	—	—	150	kHz
		5V		—	—	300	kHz
f <sub>CLK2</sub>	Serial Data Clock ( $\overline{RD}$ Pin)	3V	Duty cycle 50%	—	—	75	kHz
		5V		—	—	150	kHz
t <sub>CS</sub>	Serial Interface Reset Pulse Width (Figure 3)	—	$\overline{CS}$	—	250	—	ns
t <sub>CLK</sub>	$\overline{WR}$ , $\overline{RD}$ Input Pulse Width (Figure 1)	3V	Write mode	3.34	—	—	$\mu$ s
			Read mode	6.67	—	—	
		5V	Write mode	1.67	—	—	$\mu$ s
			Read mode	3.34	—	—	
t <sub>r</sub> , t <sub>f</sub>	Rise/Fall Time Serial Data Clock Width (Figure 1)	3V	—	—	120	—	ns
		5V		—	—	—	—
t <sub>su</sub>	Setup Time for DATA to $\overline{WR}$ , RD Clock Width (Figure 2)	3V	—	—	120	—	ns
		5V		—	—	—	—
t <sub>h</sub>	Hold Time for DATA to $\overline{WR}$ , RD Clock Width (Figure 2)	3V	—	—	120	—	ns
		5V		—	—	—	—
t <sub>su1</sub>	Setup Time for $\overline{CS}$ to $\overline{WR}$ , $\overline{RD}$ Clock Width (Figure 3)	3V	—	—	100	—	ns
		5V		—	—	—	—
t <sub>h1</sub>	Hold Time for $\overline{CS}$ to $\overline{WR}$ , $\overline{RD}$ Clock Width (Figure 3)	3V	—	—	100	—	ns
		5V		—	—	—	—



## Functional Description

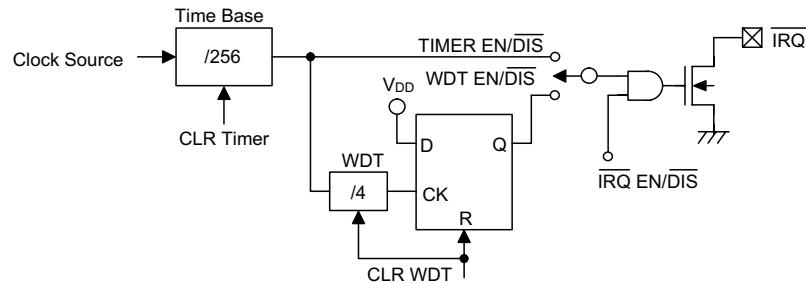
### Display memory – RAM structure

The static display RAM is organized into  $192 \times 4$  bits and stores the display data. The contents of the RAM are directly mapped to the contents of the LCD driver. Data in the RAM can be accessed by the READ, WRITE and READ-MODIFY-WRITE commands. The following is a mapping from the RAM to the LCD patterns.



### Time base and Watchdog Timer – WDT

The time base generator and WDT share the same divided (/256) counter. TIMER DIS/EN/CLR , WDT DIS/EN/CLR and IRQ EN/DIS are independent from each other. Once the WDT time-out occurs, the IRQ pin will remain at logic low level until the CLR WDT or the IRQ DIS command is issued.



Timer and WDT configurations

If an external clock is selected as the source of system frequency, the SYS DIS command turns out invalid and the power down mode fails to be carried out until the external clock source is removed.

#### Buzzer tone output

A simple tone generator is implemented in the HT1626. The tone generator can output a pair of differential driving signals on the BZ and B<sub>Z</sub> which are used to generate a single tone.

#### Command format

The HT1626 can be configured by the software setting. There are two mode commands to configure the HT1626 resource and to transfer the LCD display data.

The following are the data mode ID and the command mode ID:

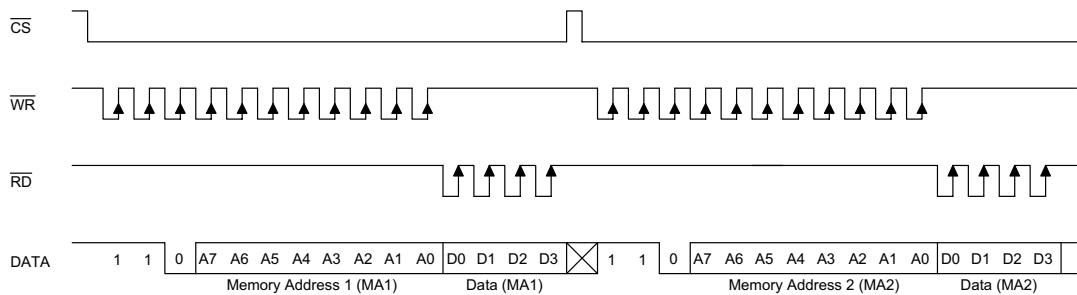
Operation	Mode	ID
READ	Data	1 1 0
WRITE	Data	1 0 1
READ-MODIFY-WRITE	Data	1 0 1
COMMAND	Command	1 0 0

If successive commands have been issued, the command mode ID can be omitted. While the system is operating in the non-successive command or the non-successive address data mode, the CS pin should be set to "1", and the previous operation mode will be reset also. The CS pin returns to "0", a new operation mode ID should be issued first.

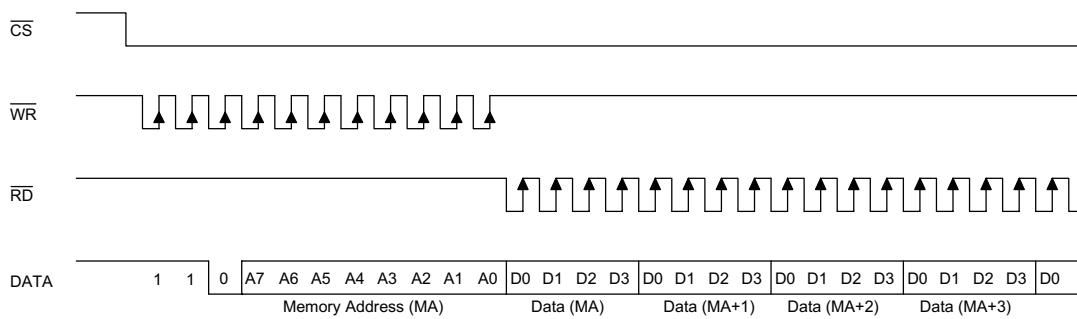
Name	Command Code	Function
TONE OFF	0000-1000-X	Turn-off tone output
TONE 4K	010X-XXXX-X	Turn-on tone output, tone frequency is 4kHz
TONE 2K	0110-XXXX-X	Turn-on tone output, tone frequency is 2kHz

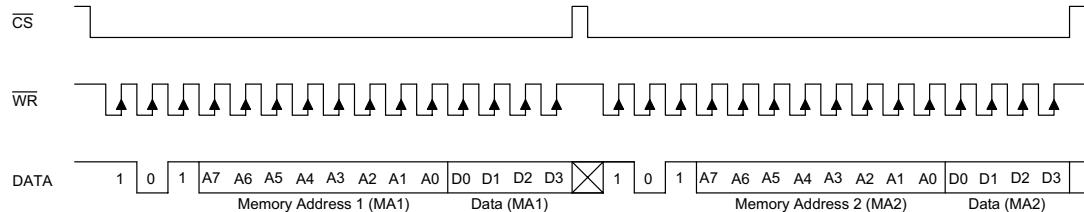
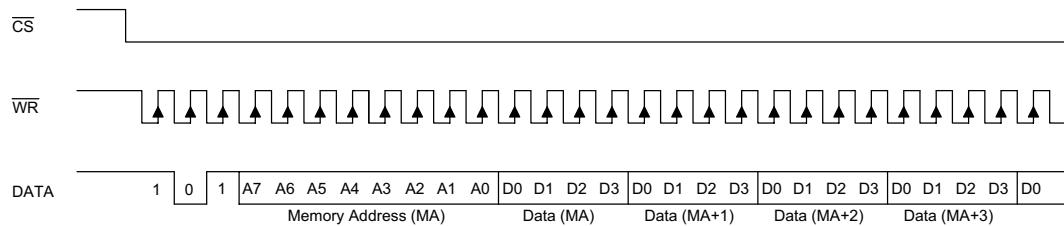
## Timing Diagrams

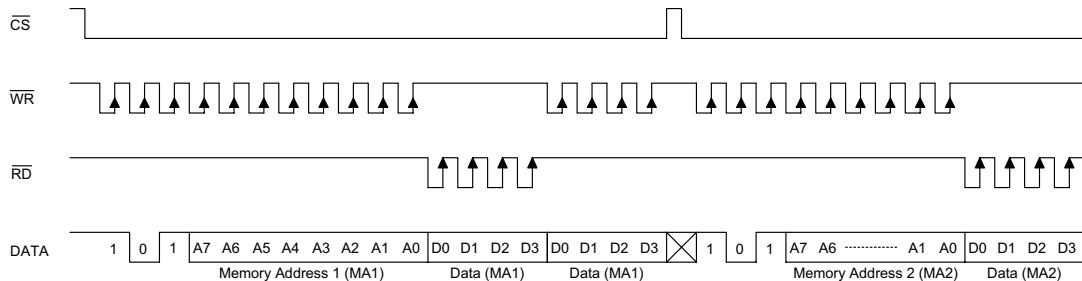
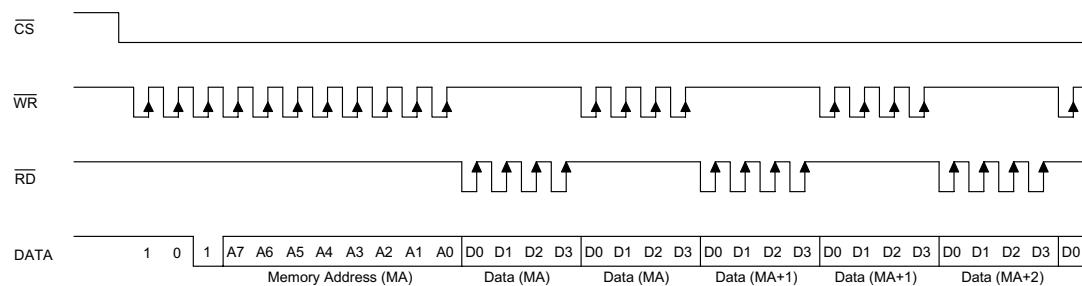
### READ mode (command code : 1 1 0)

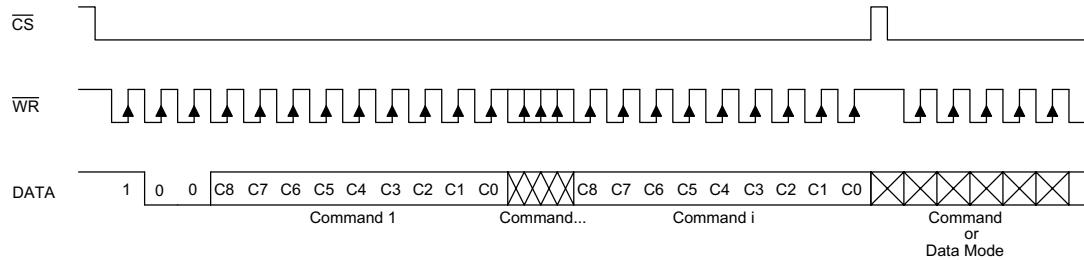
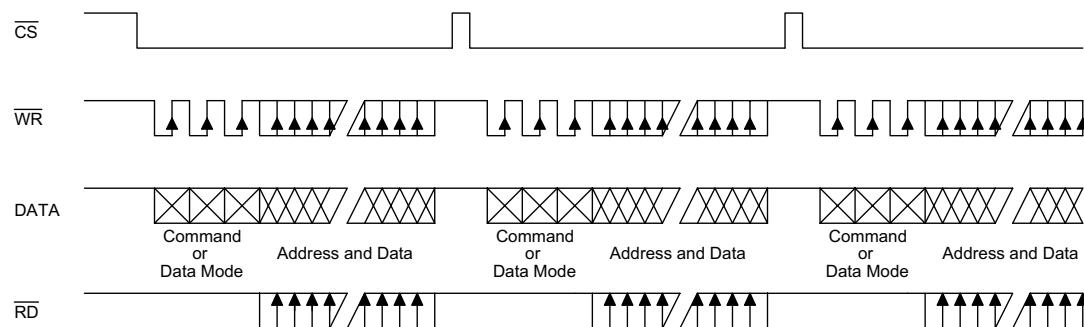


### READ mode (successive address reading)

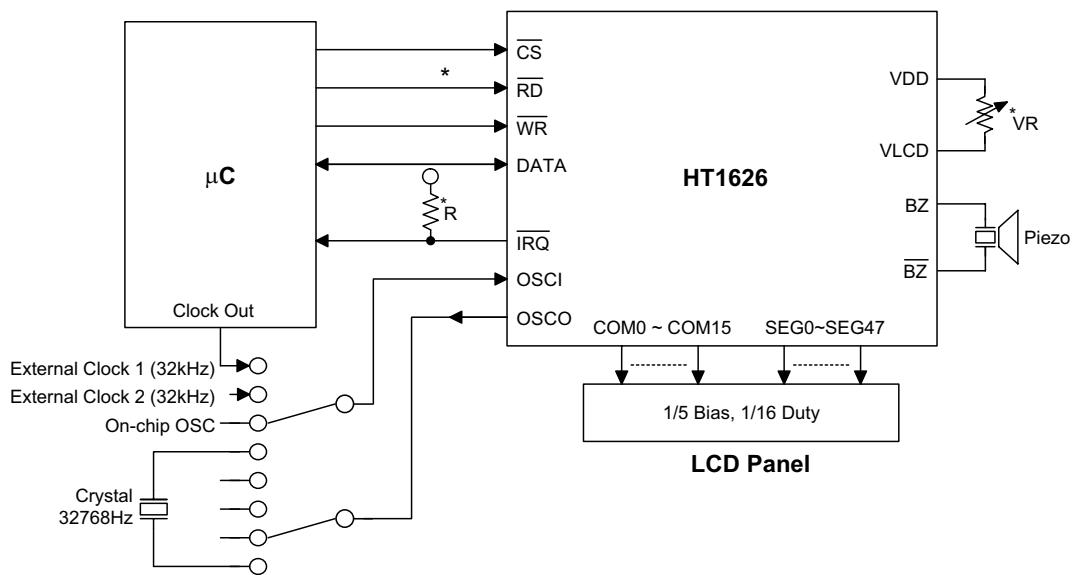


**WRITE mode (command code : 1 0 1)**

**WRITE mode (successive address writing)**


**READ-MODIFY-WRITE mode (command code : 1 0 1)**

**READ-MODIFY-WRITE mode (successive address accessing)**


**Command mode (command code : 1 0 0)**

**Mode (data and command mode)**


## Application Circuits



\*Note: The connection of  $\overline{\text{IRQ}}$  and  $\overline{\text{RD}}$  pin can be selected depending on the requirement of the  $\mu\text{C}$ .

The volatage applied to  $V_{\text{LCD}}$  pin must be lower than  $V_{\text{DD}}$ .

Adjust VR to fit LCD display, at  $V_{\text{DD}}=5\text{V}$ ,  $V_{\text{LCD}}=4\text{V}$ ,  $VR=15\text{k}\Omega \pm 20\%$ .

Adjust R (external pull-high resistance) to fit user's time base clock.

**Instruction Set Summary**

Name	ID	Command Code	D/C	Function	Def.
READ	<b>1 1 0</b>	A7A6A5A4A3A2A1A0D0D1D2D3	D	Read data from the RAM	
WRITE	<b>1 0 1</b>	A7A6A5A4A3A2A1A0D0D1D2D3	D	Write data to the RAM	
READ-MODIFY-WRITE	<b>1 0 1</b>	A7A6A5A4A3A2A1A0D0D1D2D3	D	Read and Write data to the RAM	
SYS DIS	<b>1 0 0</b>	0000-0000-X	C	Turn off both system oscillator and LCD bias generator	Yes
SYS EN	<b>1 0 0</b>	0000-0001-X	C	Turn on system oscillator	
LCD OFF	<b>1 0 0</b>	0000-0010-X	C	Turn off LCD display	Yes
LCD ON	<b>1 0 0</b>	0000-0011-X	C	Turn on LCD display	
TIMER DIS	<b>1 0 0</b>	0000-0100-X	C	Disable time base output	Yes
WDT DIS	<b>1 0 0</b>	0000-0101-X	C	Disable WDT time-out flag output	Yes
TIMER EN	<b>1 0 0</b>	0000-0110-X	C	Enable time base output	
WDT EN	<b>1 0 0</b>	0000-0111-X	C	Enable WDT time-out flag output	
TONE OFF	<b>1 0 0</b>	0000-1000-X	C	Turn off tone outputs	Yes
CLR TIMER	<b>1 0 0</b>	0000-1101-X	C	Clear the contents of the time base generator	
CLR WDT	<b>1 0 0</b>	0000-1111-X	C	Clear the contents of the WDT stage	
RC 32K	<b>1 0 0</b>	0001-10XX-X	C	System clock source, on-chip RC oscillator	Yes
EXT (XTAL) 32K	<b>1 0 0</b>	0001-11XX-X	C	System clock source, external 32kHz clock source or crystal oscillator 32.768kHz	
TONE 4K	<b>1 0 0</b>	010X-XXXX-X	C	Tone frequency output: 4kHz	
TONE 2K	<b>1 0 0</b>	0110-XXXX-X	C	Tone frequency output: 2kHz	
IRQ DIS	<b>1 0 0</b>	100X-0XXX-X	C	Disable IRQ output	Yes
IRQ EN	<b>1 0 0</b>	100X-1XXX-X	C	Enable <u>IRQ</u> output	
F1	<b>1 0 0</b>	101X-0000-X	C	Time base clock output: 1Hz The WDT time-out flag after: 4s	
F2	<b>1 0 0</b>	101X-0001-X	C	Time base clock output: 2Hz The WDT time-out flag after: 2s	
F4	<b>1 0 0</b>	101X-0010-X	C	Time base clock output: 4Hz The WDT time-out flag after: 1s	

Name	ID	Command Code	D/C	Function	Def.
F8	<b>1 0 0</b>	101X-0011-X	C	Time base clock output: 8Hz The WDT time-out flag after: 1/2 s	
F16	<b>1 0 0</b>	101X-0100-X	C	Time base clock output: 16Hz The WDT time-out flag after: 1/4 s	
F32	<b>1 0 0</b>	101X-0101-X	C	Time base clock output: 32Hz The WDT time-out flag after: 1/8 s	
F64	<b>1 0 0</b>	101X-0110-X	C	Time base clock output: 64Hz The WDT time-out flag after: 1/16 s	
F128	<b>1 0 0</b>	101X-0111-X	C	Time base clock output: 128Hz The WDT time-out flag after: 1/32 s	Yes
TEST	<b>1 0 0</b>	1110-0000-X	C	Test mode, user don't use.	
NORMAL	<b>1 0 0</b>	1110-0011-X	C	Normal mode	Yes

Note: X : Don't care

A7~A0 : RAM address

D3~D0 : RAM data

D/C : Data/Command mode

Def. : Power on reset default

All the bold forms, namely **1 1 0**, **1 0 1**, and **1 0 0**, are mode commands. Of these, **1 0 0** indicates the command mode ID. If successive commands have been issued, the command mode ID except for the first command will be omitted. The source of the tone frequency and of the time base/WDT clock frequency can be derived from an on-chip 32kHz RC oscillator, a 32.768kHz crystal oscillator, or an external 32kHz clock. Calculation of the frequency is based on the system frequency sources as stated above. It is recommended that the host controller should initialize the HT1626 after power on reset, for power on reset may fail, which in turn leads to the malfunctioning of the HT1626.

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